#### CMOS 4-Bit Microcontroller

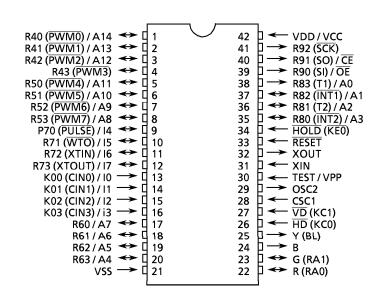
### **TMP47P1637VN**

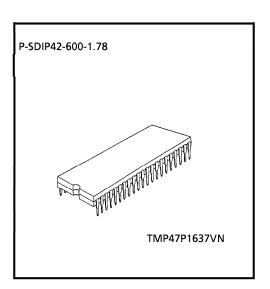
The 47P1637V is the OTP microcontroller with 128 Kbits PROM. For program operation, the programming is achieved by using with EPROM programmer (TMM27256AD type) and adaptor socket. The function of this device is exactly same as the 47C637/837 and 47C1237/1637.

Part No.	ROM	RAM	Package	Adaptor socket
TMP47P1637VN	OTP 16384 × 8-bit	512 × 4-bit	P-SDIP42-600-1.78	BM1168

### **Pin Assignment (Top View)**

P-SDIP42-600-1.78





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● For a discussion of how the reliability of microcontrollers can be predicted, please refer to Section 1.3 of the chapter

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# **Pin Function**

The 47P1637V has MCU mode and PROM mode.

(1) MCU mode

The 47C637, 47C837, 47C1237 and the 47C1637 are pin compatible (TEST pin for out-going test. Be fixed to low level).

# (2) PROM mode

Pin Name	Input / Output	Functions	Pin Name (MCU mode)
A14 to A12			R40 to R42
A11 to A8	Input	Address inputs	R50 to R53
A7 to A4	трис	Address inputs	R60 to R63
A3 to A0			R80 to R83
17 to 14	I/O	Data Inputs / outputs	R73 to R70
13 to 10		Data inputs/ outputs	K03 to K00
CE	Input	Chip Enable input	R91
ŌĒ	mput	Output Enable input	R90
VPP		+ 12.5V / 5V (Program supply voltage)	TEST
vcc	Power supply	+5 V	VDD
VSS		0 V	VSS
HD, VD	Input	Be fixed to low level	
R43			
R92	I/O	Open	
G, R		Open	
Υ, Β	Output		
RESET	Input	PROM mode setting pin. Be fixed to low level.	
HOLD	Input	r redivinious setting pin. Be fixed to low level.	
XIN	Input	Resonator connecting pins	
хоит	Output	nesonator connecting pins	
OSC 1	Input	Onen	
OSC 2	Output	Open	

### **Operational Description**

The following is an explanation of hardware configuration and operation in relation to the 47P1637V. The 47P1637V is the same as the 47C1237/1637 except that an OTP is used instead of a built-in mask ROM.

### 1. Operation mode

The 47P1637V has an MCU mode and a PROM mode.

### 1.1 MCU mode

The MCU mode is set by fixing the TEST / VPP pin at the "L" level. Operation in the MCU mode is the same as the 47C1237/1637, except that the TEST / VPP pin does not have a built in pull-down resistor and cannot be used open.

### 1.1.1 Program Memory

The program storage area is the same as the 47C1637.

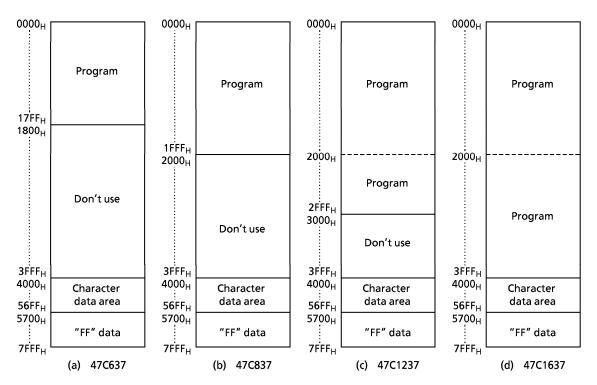


Figure 1-1. Program area

Note: "FF" data have to be written in address "\*\*\* $9_H$ " to "\*\*\* $F_H$ " of character data area. And "1" data heve to be written in bit "7" of character data area.

### 1.1.2 Data Memory

The 47P1637V has two built-in 256  $\times$  4-bit data memory banks (DMB0, DMB1). When using the 47P1637V as the 47C637/837 evaluator, DMB1 has address space at addresses 00-FF<sub>H</sub>, but do not write data to 80<sub>H</sub> or following address, DMB0 includes a special function common area so this need not be taken into consideration.

# 1.1.3 Input / Output Circuitry

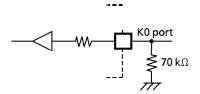
# (1) Control pins

This is the same as for the 47C1237/1637 except that there is no built in pull-down resistor for the TEST pin. Input / output circuitry of the 47P1637V control pins is shown below.

Control Pin	I/O	Circuitry	Remarks
XIN XOUT	Input Output	OSC. enable  R  R  R  R  R  XIN  XOUT	Resonator connecting pins $R = 1 \ k\Omega \ (typ.)$ $R_f = 1.5 \ M\Omega \ (typ.)$ $R_O = 2 \ k\Omega \ (typ.)$
XTIN XTOUT	Input Output	OSC. enable  R  R  R  Rfs  RFS  XTIN  XTOUT	Resonator connecting pins $ (R = 1 \text{ k}\Omega \text{ typ.}) $ $ (R_{fs} = 6 \text{ M}\Omega \text{ typ.}) $ $ (R_O = 220 \text{ k}\Omega \text{ typ.}) $
RESET	Input	R <sub>IN</sub> R W	Hysteresis input Contained pull-up resistor $R_{IN} = 220 \text{ k}\Omega$ (typ.) $R = 1 \text{ k}\Omega$ (typ.)
HOLD (KEO)	Input (Input)	$-\!$	Hysteresis input (Sence input) $R = 1 \text{ k}\Omega \text{ (typ.)}$
TEST	Input		Not contained pull-down resistor $R = 1 k\Omega \text{ (typ.)}$
OSC1 OSC2	Input Output	OSC. enable W R <sub>f</sub> R <sub>O</sub> OSC1 OSC2	Oscillation terminals for OSD $R = 1 k\Omega \text{ (typ.)}$ $R_f = 1.5 M\Omega \text{ (typ.)}$ $R_O = 2 k\Omega \text{ (typ.)}$
HD VD	Input		Synchronous signal input Hysteresis input $R=1\ k\Omega\ \ \mbox{(typ.)}$

### (2) I/O port

The input/output circuit of the 47P1637V is the same as I/O code PA of the 47C637/837 and 47C1237/1637. When this chip is used as evaluator with the I/O code, it is necessary to provide such as external resistors.



Pull-down resistor for code PC

Figure 1-2. Example of External Circuitry

The input / output circuitry of the 47P1637V I/O port is as follows.

Port	I/O	Input / Output Circuitry (code: PA)	Remarks
К0	Input	~ R	Not contained Pull-up or pull-down resistor $R = 1 \text{ k}\Omega \text{ (typ.)}$
R4 R5 RA	I/O	DISABLE	Tri-state I/O Initial "Hi-Z" R = 1 kΩ (typ.)
R6	1/0	→ N R R R	Sink open drain Initial "Hi-Z" High drive carrent $I_{OL} = 20$ mA (typ.) $R = 1 \text{ k}\Omega$ (typ.)
R7	I/O	→ No. 10 to	Sink open drain Initial "Hi-Z" R = 1 kΩ (typ.)
R8 R9	I/O		Sink open drain Initial "Hi-Z" Hysteresis input $R=1k\Omega$ (typ.)

### 1.2 PROM mode

The PROM mode is set by setting the RESET, HOLD, pins to the "L" level. The PROM mode can be used as a general-purpose PROM writer for program writing and verification. (A high-speed program mode is used set the ROM type the same as for the TMM 27256AD)

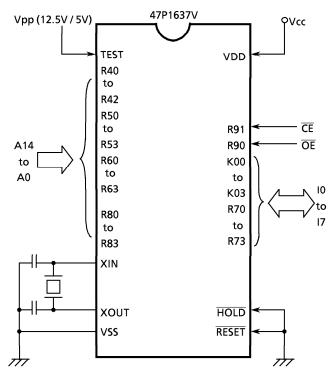
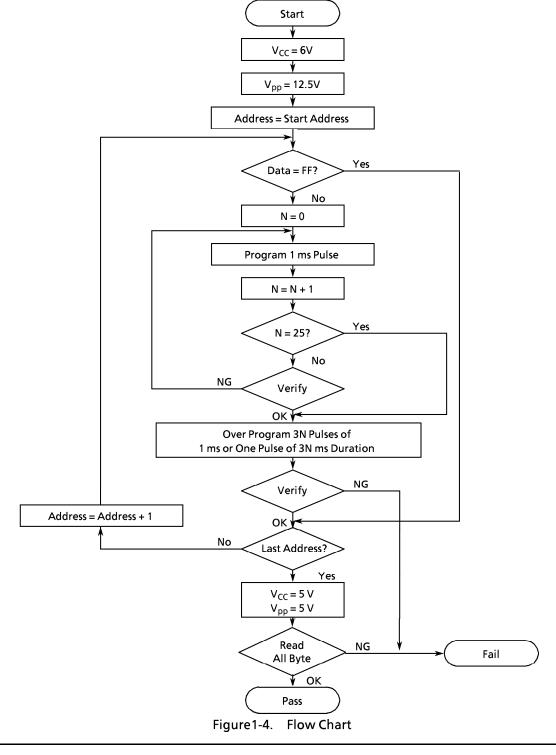


Figure 1-3. Setting for PROM mode

### 1.2.1 Programming flow chart (High-speed programming mode)

The high-speed programming mode is activated by applying the programming voltage of Vpp (12.5 V) under Vcc = 6V. After addresses and input data are stable, the programming is performed by supplying 1ms of program pulse (single) to  $\overline{CE}$  input. The data is verified by using Program Verify mode. If the program data is not correct, additional 1ms of program pulse is supplied until the programming operates correctly (max. 25 times). Further, program pulse with a pulse width 3 times that of required for programming (number of programming X 1 ms) is resupplied. This completes programming of one address.

Subsequently, repeat the same procedures by changing addresses and input data. When all programming has been ended, the data in all address should be verified under Vcc = Vpp = 5 V.



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### **Electrical Characteristics**

Absolute Maximum Ratings  $(V_{SS} = 0 V)$ 

Parameter	Symbol	Pins	Ratings	Unit	
Supply Voltage	$V_{DD}$		– 0.3 to 7	V	
Program Voltage	$V_{PP}$	TEST / VPP pin	- 0.3 to 14.0	V	
Input Voltage	V <sub>IN</sub>		- 0.3 to V <sub>DD</sub> + 0.3	V	
Outrout Valtage	V <sub>OUT1</sub>	Except sink open drain pin, R7 port	- 0.3 to V <sub>DD</sub> + 0.3	.,	
Output Voltage	V <sub>OUT2</sub>	Sink open drain pin except R7 port	- 0.3 to 10	<b>-</b>	
Outrot Compat (Dantaia)	I <sub>OUT1</sub>	OUT1 R6 port		4	
Output Current (Per 1 pin)	I <sub>OUT2</sub>	R7, R8, R9 port	3.2	mA	
Output Current (Total)	Σ I <sub>OUT1</sub>	R6 port	60	mA	
Power Dissipation	PD		600	mW	
Soldering Temperature (time)	Tsld		260 (10 s)	°C	
Storage Temperature	Tstg		– 55 to 125	°C	
Operating Temperature	Topr		- 30 to 70	°C	

Note: The absolute maximum ratings are rated values which must not be exceeded during operation, even for an instant.

Any one of the ratings must not be exceeded. If any absolute maximum rating is exceeded, a device may break down or its performance may be degraded, causing it to catch fire or explode resulting in injury to the user. Thus, when designing products which include this device, ensure that no absolute maximum rating value will ever be exceeded.

Recommended Opeating Conditions

 $(V_{SS} = 0 \text{ V, Topr} = -30 \text{ to } 70^{\circ}\text{C})$ 

Parameter	Symbol	Pins	Conditions	Min	Max	Unit
			In the Normal mode	4.5		
Supply Voltage	$V_{DD}$		In the SLOW mode	2.7	6.0	v
			In the HOLD mode	2.0		
	V <sub>IH1</sub>	Except Hysteresis Input	$V_{DD} \ge 4.5  V$	$V_{DD} \times 0.7$	V <sub>DD</sub>	
Input High Voltage	$V_{IH2}$	Hysteresis Input	V <sub>DD</sub> ≦ 4.3 V	$V_{DD} \times 0.75$		v
	V <sub>IH3</sub>		$V_{DD}$ < 4.5 V	$V_{DD} \times 0.9$		
	$V_{IL1}$	Except Hysteresis Input	V > 4 E V		$V_{DD} \times 0.3$	
Input Low Voltage	$V_{IL2}$	Hysteresis Input	$V_{DD} \ge 4.5 V$	0	$V_{DD} \times 0.25$	v
	$V_{IL3}$		$V_{DD}$ < 4.5 V		$V_{DD} \times 0.1$	
	fc	XIN, XOUT		0.4	6.0	MHz
Clock Frequency	fs	XTIN, XTOUT		30.0	34.0	kHz
	f <sub>OSD</sub>	OSC1, OSC2		_	8.0	MHz

Note 1: The recommended operating conditions for a device are operating conditions under which it can be guaranteed that the device will operate as specified. If the device is used under operating conditions other than the recommended operating conditions (supply voltage, operating temperature range, specified AC/DC values etc.), malfunction may occur. Thus, when designing products which include this device, ensure that the recommended operating conditions for the device are always adhered to.

Note 2: Input Voltage VIH3 , VIL3: in the SLOW or HOLD mode

### D.C. Characteristics

 $(V_{SS} = 0 \text{ V}, \text{ Topr } = -30 \text{ to } 70^{\circ}\text{C})$ 

Parameter	Symbol	Pins	Conditions	Min	Тур.	Max	Unit
Hysteresis Voltage	V <sub>HS</sub>	Hysteresis Input		_	0.7	_	V
Input Current	I <sub>IN1</sub>	K0 port, TEST, RESET, HOLD	V <sub>DD</sub> = 5.5 V,	_	_	± 2	μA
·	I <sub>IN2</sub>	R port (open drain)	V <sub>IN</sub> = 5.5 V / 0 V				
Input Resistance	R <sub>IN2</sub>	RESET		100	220	450	kΩ
Output Leakage Current	I <sub>LO</sub>	Tri-state R6, R8, R9 port (open drain)	$V_{DD} = 5.5  V, \ V_{OUT} = 5.5  V$	_	_	± 2	μΑ
Output High Voltage	V <sub>OH2</sub>	R port (tri-state), OSD output	$V_{DD} = 4.5  V,  I_{OH} = -0.7  \text{mA}$	4.1	_	_	V
	V <sub>OL1</sub>	R7, R8, R9 port	$V_{DD} = 4.5 \text{ V}, \ I_{OL} = 1.6 \text{ mA}$				
Output Low Voltage	V <sub>OL2</sub>	R port (tri-state), OSD output	$V_{DD} = 4.5  V,  I_{OL} = 0.7  \text{mA}$	_	_	0.4	V
Output Low Current	l <sub>OL</sub>	R6 port	$V_{DD} = 4.5  V, \ V_{OL} = 1.0  V$	_	20	_	mA
Supply Current (in the Nomal mode)	I <sub>DD</sub>		$V_{DD} = 5.5 V$ fc = 4 MHz		3	6	mA
Supply Current (in the SLOW mode)	I <sub>DDS</sub>		V <sub>DD</sub> = 3.0 V	_	30	60	μΑ
Supply Current (in the HOLD mode)	I <sub>DDH</sub>		V <sub>DD</sub> = 5.5 V	_	0.5	10	μA

Note 1: Typ. values show those at  $T_{opr} = 25$  °C, VDD = 5V. Note 2: Input Current  $I_{IN1}$ : The current through resistor is not included, when the pull-up/pull-down resistor is

contained. Note 3: Supply Current:  $V_{IN} = 5.3V/0.2V$ 

The K0 port is open when the pull-up / pull-down resistor is contained. The voltage applied to the R port is within the valid range  $V_{IL}$  or  $V_{IH}$ .

### A/D Conversion Characterristics

Parameter	SYmbol	Pins	Conditions	Min	Тур.	Max	Unit
Analog Input Voltage	V <sub>AIN</sub>	CIN3 to CIN0		V <sub>SS</sub>	-	$V_{DD}$	٧
A/D Conversion Error	-			-	-	± 1/2	LSB

A.C. Characteristics

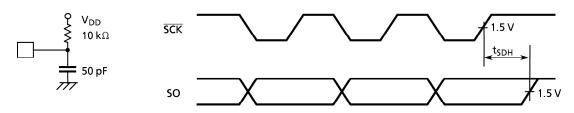
 $(V_{SS} = 0 \text{ V}, V_{DD} = 4.5 \text{ to } 6.0 \text{ V}, \text{ Topr} = -30 \text{ to } 70^{\circ}\text{C})$ 

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
In atmosti an Cool a Time	4	in the NORMAL mode	1.3	_	20	
Instruction Cycle Time	tcy	in the SLOW mode	235		267	μS
High level Clock Pulse Width	t <sub>WCH</sub>	For external clock operation	80	_	_	ns
Low level Clock Pulse Width	t <sub>WCL</sub>	Tor external clock operation	80		_	""
Shift Data Hold Time	t <sub>SDH</sub>		0.5 tcy – 300	_	_	ns

Note: Shift data Hold Time

External circuit for SCK pin and SO pin

Serial port (completion of transmission)



**Recommended Oscillating Conditions** 

 $(V_{SS} = 0 \text{ V}, V_{DD} = 4.5 \text{ to } 6.0 \text{ V}, \text{ Topr} = -30 \text{ to } 70^{\circ}\text{C})$ 

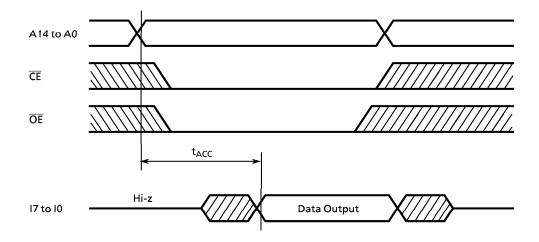
Recommended oscillating conditions of the 47P1637V are equal to those of the 47C637/837 and 47C1237/1637.

DC/AC characteristics

 $(V_{SS} = 0 V)$ 

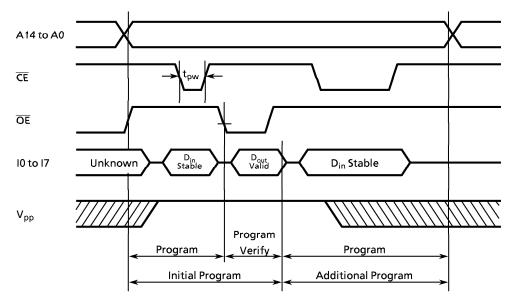
### (1) Read Operation

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Output Level High Voltage	V <sub>IH4</sub>		V <sub>CC</sub> × 0.7	_	V <sub>CC</sub>	٧
Output Level Low Voltage	V <sub>IL4</sub>		0	-	V <sub>CC</sub> × 0.3	٧
Supply Voltage	V <sub>CC</sub>		4.75		6.0	v
Programming Voltage	V <sub>PP</sub>		4.75 –		6.0	, v
Address Access Time	t <sub>ACC</sub>	V <sub>CC</sub> = 5.0 ± 0.25 V	0	_	350	ns



### (2) High Speed Programming Operation

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Input High Voltage	V <sub>IH4</sub>		V <sub>CC</sub> × 0.7	ı	V <sub>CC</sub>	٧
Input Low Voltage	V <sub>IL4</sub>		0	-	V <sub>CC</sub> × 0.3	>
Supply Voltage	V <sub>CC</sub>		5.75	_	6.25	V
V <sub>PP</sub> Power Supply Voltage	V <sub>PP</sub>		12.25	12.5	12.75	٧
Programming Pulse Width	t <sub>PW</sub>	V <sub>CC</sub> = 6.0 ± 0.25 V	0.95	1.0	1.05	ms



Note: An electrical shield by metal shield plate on the surface of the IC package should be recommendable in order to prevent the device from the high electric fieldstress applied from CRT (Cathode Ray Tube) for continuous reliable operation.

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